

AN 130:19574 HCA  
TI Copper alloy having high stamping processability for  
electronic applications  
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SO Jpn. Kokai Tokkyo Koho, 8 pp.  
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PI	JP 10287939	A2	19981027	JP 1997-100279	19970417
AB	The Cu alloy comprises Cr 0.1-0.4, Zr .gtoreq.0 and <0.2, rare earth metal 0.002-0.2, Pb and/or Bi 0.002-0.2 wt.% (in total), and Cu bal. and the alloy has crystd. substances and deposited substances with diam. <3 .mu.m and crystal grain size <20 .mu.m. Alternatively, the above Cu alloy may also contain 0.01-1.0 wt.% Sn, Mg, Ni, Ag, Zn, Si, and/or Mn in total. The Cu alloy has high strength and cond. and is useful for lead frames for semiconductor device such as integrated circuit or for heat medium such as terminals, connectors, contacts, and so on.				